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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/895,524	06/28/2001	Rafael A. Mena	TI-29612	8193
23494	7590 03/22/2006		EXAMINER	
TEXAS INSTRUMENTS INCORPORATED			FOURSON III, GEORGE R	
P O BOX 655474, M/S 3999 DALLAS, TX 75265			ART UNIT	PAPER NUMBER
DALLAS, 17	13203		2823	

Please find below and/or attached an Office communication concerning this application or proceeding.

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	Application No.	Applicant(s)				
	09/895,524	MENA ET AL.				
Office Action Summary	Examiner	Art Unit				
	George Fourson	2823				
The MAILING DATE of this communication app Period for Reply	ears on the cover sheet with the c	orrespondence address				
A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.  - Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.  - If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.  - Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).						
Status						
1) Responsive to communication(s) filed on 04 Ja	nuary 2006.					
· ·						
3) Since this application is in condition for allowan	·=					
closed in accordance with the practice under E	x parte Quayle, 1935 C.D. 11, 45	3 O.G. 213.				
Disposition of Claims						
<ul> <li>4) ☐ Claim(s) 1-12 is/are pending in the application.</li> <li>4a) Of the above claim(s) is/are withdrawn from consideration.</li> <li>5) ☐ Claim(s) is/are allowed.</li> <li>6) ☐ Claim(s) 1-12 is/are rejected.</li> <li>7) ☐ Claim(s) is/are objected to.</li> <li>8) ☐ Claim(s) are subject to restriction and/or election requirement.</li> </ul>						
Application Papers						
9) The specification is objected to by the Examiner  10) The drawing(s) filed on is/are: a) access Applicant may not request that any objection to the or Replacement drawing sheet(s) including the correction of the original transfer of the correction is objected to by the Examiner of the correction of the corre	epted or b) objected to by the Edrawing(s) be held in abeyance. See ion is required if the drawing(s) is obj	e 37 CFR 1.85(a). ected to. See 37 CFR 1.121(d).				
Priority under 35 U.S.C. § 119						
12) Acknowledgment is made of a claim for foreign a) All b) Some * c) None of:  1. Certified copies of the priority documents 2. Certified copies of the priority documents 3. Copies of the certified copies of the prior application from the International Bureau * See the attached detailed Office action for a list	s have been received. s have been received in Applicati ity documents have been receive ı (PCT Rule 17.2(a)).	on No ed in this National Stage				
Attachment(s)						
1) Notice of References Cited (PTO-892)  4) Interview Summary (PTO-413)						
Notice of Draftsperson's Patent Drawing Review (PTO-948)     Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)     Paper No(s)/Mail Date	Paper No(s)/Mail Da 5) Notice of Informal P 6) Other:	ate latent Application (PTO-152)				
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The text of those sections of Title 35, U.S. Code not included in this action can be found in a prior Office action.

Claims 1 and 8 are rejected under 35 U.S.C. 102(a) as being anticipated by Tran et al.

Reliance is now on Tran et al which was incorporated by reference by Ngo et al, previously relied on. Tran et al discloses in figure 4 HDP oxide layer 42 over patterned metal features 41 and 14 and dielectric layer 43 over HDP oxide. HDP oxide layer 42 inherently has sloped edges as indicated by Yao et al (col.1). Formation of vias and contacts to the metal leads is depicted in figure 5, for example.

Applicant argues that layer 42 of Tran et al is not encompassed by "liner layer" because it is disclosed by Tran et al that the layer fills the gaps between the metal lines. However, applicant is directed to figure 4 which shows that although the gaps are filled by the layer 42 they are not completely filled by the layer and a portion of the gaps is filled by material 43 as recited.

Claims 2,5,6 and 7 are rejected under 35 U.S.C. 103(a) as being unpatentable over Tran et al as applied to claims 1 and 8 above, and further in view of Lee.

Tran et al does not disclose the etch-dep ratio or the shape of the HDP oxide on the metal leads.

Lee discloses that in HDP deposition an etch-dep ratio resulting in a 45 degree angle is suitable in gap filling (col.1, lines 24-36).

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It would have been obvious to one of ordinary skill in the art to combine the teachings of Tran et al and Lee et al to enable the HDP oxide layer of Tran et al to be formed according to the teachings of Lee and further to enable desirable gap filling characteristics of the HDP oxide.

Lee discloses formation of pyramidal and trapezoidal shapes on the patterned features depending on the width of the features. It would have been obvious to one of ordinary skill in the art to form the metal leads having widths that result in both pyramidal and trapezoidal shapes of the HDP oxide on the leads depending on desired current carrying characteristics of the metal leads.

Claims 3,4,10 and 11 are rejected under 35 U.S.C. 103(a) as being unpatentable over Tran et al as applied to claims 1 and 8 above, and further in view of Wolf, Vol.2.

Tran et al does not disclose use of PETEOS, silane based oxide or spin-on glass as the dielectric layer. The reference discloses use of TEOS (col.6, line 49) and also discloses use of any of the dielectrics conventionally employed (col.7, lines 26-30).

Wolf, Vol.2, discloses use of PETEOS as an interlevel dielectric layer (p.194, last paragraph), silane based P doped oxide as an interlevel dielectric layer (p.195, last paragraph) and SOG as an interlevel dielectric layer (fig. 4-32). It would have been obvious to one of ordinary skill in the art to combine the teachings of Wolf, Vol.2 with those of Tran et al to enable the dielectric layer of Tran et al to be formed of one of the materials disclosed to be suitable for such a purpose by Wolf, Vol.2.

Claim 9 is rejected under 35 U.S.C. 103(a) as being unpatentable over Tran et al as applied to claims 1 and 8 above, and further in view of Tsai et al.

Tran et al does not disclose formation of the HDP oxide layer using F doped oxide.

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Tsai et al discloses formation of multilevel interconnects including depositing phosphorous doped HDP liner layer 204 over metal leads 202 followed by gap filling layer 206 (col.3, lines 10-29 and fig.2A). It would have been obvious to one of ordinary skill in the art to combine the teachings of Tran et al and Tsai et al to enable the HDP oxide layer of Tran et al to be formed according to the method of Tsai et al.

Claim 12 is rejected under 35 U.S.C. 103(a) as being unpatentable over Tran et al as applied to claims 1 and 8 above, and further in view of AAPA.

Tran et al does not disclose use of HSQ as the dielectric layer.

Applicant admits use of HSQ as an interlevel dielectric layer (instant page 1, lines 25-26) to have been known prior to applicant's invention.

It would have been obvious to one of ordinary skill in the art to combine the known method of forming an interlevel dielectric with the teachings of Tran et al to enable the interlevel dielectric of Tran et al to be formed according to the known method.

THIS ACTION IS MADE FINAL. Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory

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action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the mailing date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to George Fourson whose telephone number is (571)272-1860272-1860. The examiner can normally be reached on Monday through Friday.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Smith Matthew, can be reached on (571) 272-1855. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

George Fourson Primary Examiner Art Unit 2823

GFourson March 18, 2006